

Title (en)
EPOXY RESIN BASED SOLDER PASTE

Title (de)
Lötpaste auf Epoxidharzbasis

Title (fr)
PATE A SOUDER A BASE DE RESINE EPOXY

Publication
EP 0870329 A1 19981014 (EN)

Application
EP 96928056 A 19960809

Priority
• US 9612761 W 19960809
• US 51404995 A 19950811
• US 64491196 A 19960528

Abstract (en)
[origin: WO9707542A1] A method of making low and high mass assemblies at surface mount profile conditions utilizing a solder paste have a binder comprised of a thermosetting resin and cross-linking agent that also acts as a flux is described. The method of selecting the components and specific binders, including binders with a catalyst such as tin octoate are also described. The binder utilized has a gel point that is at or above the melting point of the solder powder and most preferably above such melting point.

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H01L 23/488; **H01B 1/06**; **B05D 5/12**; **B32B 27/38**; **B32B 15/08**; **C08G 59/68**; **C08G 59/40**

IPC 8 full level
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Citation (search report)
See references of WO 9707542A1

Designated contracting state (EPC)
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